

IMPROVED BURST PRESSURE OF LPCVD Si₃N₄ MEMBRANES BY NANOMETER THICK COMPRESSIVE ADLAYERS

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Si₃N₄ is a material widely used in MEMS technology. Its high mechanical strength makes Si₃N₄ attractive for applications where there is a need for ultrathin, yet robust, freestanding films, such as nanometer thick X-ray windows and support films for TEM. In this work, mechanical properties of Si₃N₄ and B-coated Si₃N₄ membranes were studied using a bulge test method. Burst pressure and corresponding membrane stress in Si₃N₄ layers were found to be significantly increased when a 3nm thick B layer was deposited on the top side of 25nm thick Si₃N₄ membranes, whereas a B layer applied to the bottom side of the membranes did not have an effect on the membrane strength. Using FEM simulations, we show that the B layer deposited at the top side decreases the maximum tensile stress in Si₃N₄ near the membrane edge, where a significant contribution to the total stress comes from bending. From this, we conclude that failure in single layer Si₃N₄ membranes during bulge test is dominated by fracture at the edge. The burst pressure of B-coated Si₃N₄ membranes was found to be higher for membranes with lower (more compressive) residual stress in B, which indicates that failure of bilayer membranes is caused by fracture initiated in the B layer.

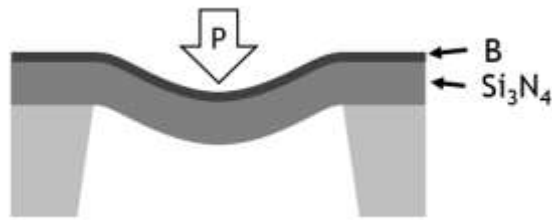


Figure 1 – Schematic of bilayer membrane during bulge testing

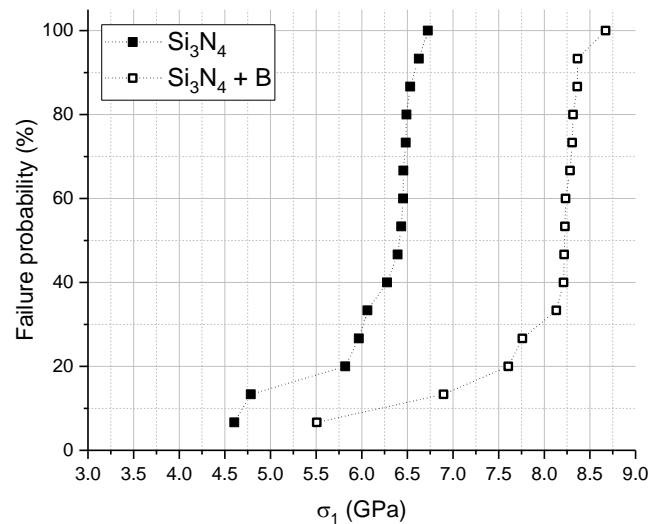


Figure 2 – Cumulative probability of failure vs. maximum membrane stress in Si₃N₄